

having a lower surface covered by the second metal coating and side surfaces uncovered by the second metal coating, said chip package further comprising a third metal coating covering the side surfaces of the second portion and the second metal coating.

18. The chip package of claim 15, said piece has a first portion embedded in the package body and a second portion located outside the package body, both the first and second portions of said piece have ~~concave~~ profiles.

B1 19. The chip package of claim 11, wherein each of the connection pads is a piece made of a single material which projects integrally from within the package body outwardly and beyond a bottom surface of the package body.

20. The chip package of claim 19, wherein said single material is copper.

21. The chip package of claim 19, wherein said piece has a first portion embedded in the package body and a second portion located outside the package body, said second portion having a lower surface covered by the second metal coating and side surfaces uncovered by the second metal coating, said chip package further comprising a third metal coating covering the side surfaces of the second portion and the second metal coating.

22. The chip package of claim 19, said piece has a first portion embedded in the package body and a second portion located outside the package body, both the first and second portions of said piece have ~~concave~~ profiles. --

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